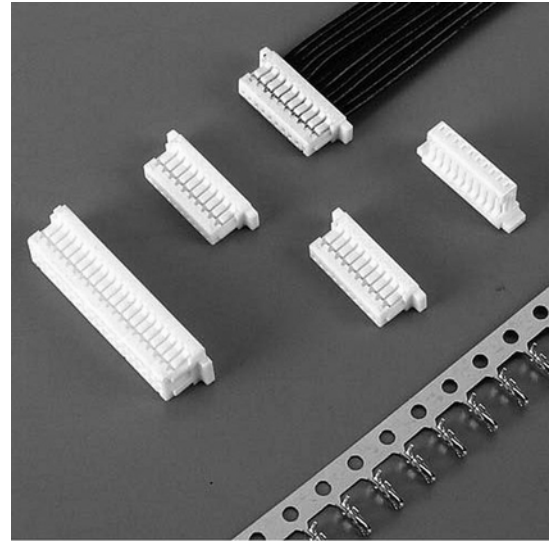


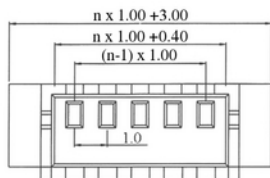
SMT-Crimp-Rast-Stift-/Buchsenleisten RM 1,00mm, stehend/liegend SMT Friction Lock Headers / Crimp Housings, 1.00mm Pitch, Vertical/Horizontal

Technische Daten / Technical Data

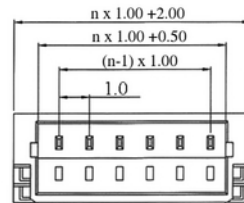
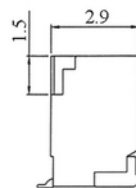
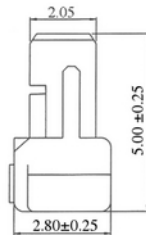
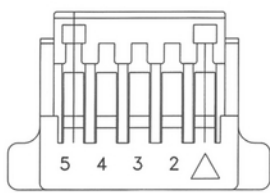
Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Aderquerschnitt <i>Applicable wire Gauge</i>	AWG 28 ... 32 <i>AWG 28 ... 32</i>
Lötbarkeit <i>Solderability</i>	IEC 60512-12A <i>IEC 60512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20mΩ <i>< 20mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 10 ⁸ Ω <i>> 10⁸Ω</i>
Spannungsfestigkeit <i>Test Voltage</i>	500V _{AC} <i>500V_{AC}</i>
Nennspannung <i>Voltage Rating</i>	50V _{AC} <i>50V_{AC}</i>
Nennstrom <i>Current Rating</i>	1A <i>1A</i>
Temperaturbereich <i>Temperature Range</i>	-40°C ... +105°C (Gehäuse -25°C ... +85°C) <i>-40°C ... +105°C (Housings -25°C ... +85°C)</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>



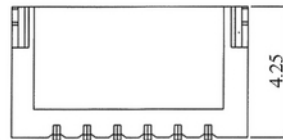
© W+P PRODUCTS



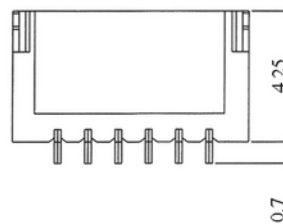
Housing



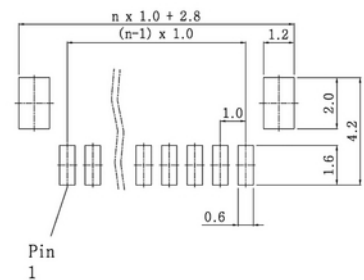
Header Straight



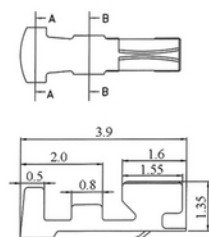
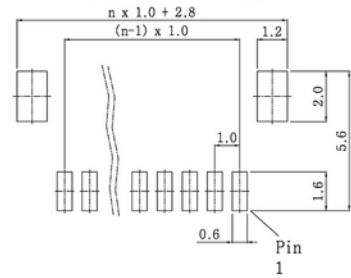
Header Right Angled



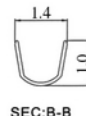
PCB Layout Straight Type



PCB Layout Angled Type



Contact



Series

5110

Contacts*

10
02 03 04 05 06
07 08 09 10 12
13 14 15 16 17
19 20

Type*

3
1 Buchsengehäuse (o. Verp.)
Housing (w/o pack.)
2 Buchsenkontakte (o. Verp.)
Crimp contacts (w/o pack.)
3 Stiftleiste gerade
Straight pin header
4 Stiftleiste gewinkelt
Right-angled pin header

Plating

50
50 Verzinkt (keine Angabe bei Gehäusen)
Tin plated (not used for housings)

Packaging*

TR
ST
TR
PPTR

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pad / *In tubes w/o Pick&Place-Pad*
TR Tape & Reel / *Tape & Reel*
PPTR Tape & Reel mit P&P-Pad / *Tape & Reel with P&P-Pad*

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

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Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

